



August 11, 2023

Subject: **Confirmation of presence at ISLPED 2023**

As general co-chair of the symposium I herewith confirm that **Erich Malan** has attended the IEEE International Symposium on Low Power Electronics and Design (ISLPED), in Vienna, Austria, on August 7-8, 2023, at the campus of TU Wien, and has presented the paper

“Enabling DVFS Side-Channel Attacks for Neural Network Fingerprinting in Edge Inference Services” authored by Erich Malan, Valentino Peluso, Andrea Calimera and Enrico Macii.

With best regards,

A handwritten signature in blue ink that reads 'Axel Jantsch'.

Axel Jantsch
Prof. of Systems on Chip